

Title (en)
ELECTRONIC COMPONENT AND PRODUCTION METHOD THEREFOR

Title (de)
ELEKTRONISCHE KOMPONENTE UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
COMPOSANT ÉLECTRONIQUE ET SON PROCÉDÉ DE FABRICATION

Publication
EP 3070720 A4 20171129 (EN)

Application
EP 14862954 A 20141112

Priority
• JP 2013235138 A 20131113
• JP 2014005679 W 20141112

Abstract (en)
[origin: EP3070720A1] A production method for an electronic component using an exterior packaging material containing a silicone resin comprises a step of dipping an element into an exterior packaging material containing a silicone resin to which aluminum hydroxide or magnesium hydroxide and a nonpolar solvent are added, an additive amount of the aluminum hydroxide or the magnesium hydroxide being controlled to a range of 60 [wt. %] or more to less than 70 [wt.%], a step of drying the exterior packaging material formed on a surface of the element to evaporate the nonpolar solvent and cause a silicone resin component to appear on a surface of the exterior packaging material, and a curing step of curing the exterior packaging material. As a result, the silicone resin can be reduced while maintaining the incombustibility and insulation withstand voltage of the exterior packaging material.

IPC 8 full level
H01C 17/02 (2006.01); **C08K 3/22** (2006.01); **C09D 7/61** (2018.01); **H01C 1/034** (2006.01); **H01C 7/10** (2006.01); **H01C 7/102** (2006.01)

CPC (source: EP KR US)
C09D 7/61 (2017.12 - EP US); **H01C 1/034** (2013.01 - EP KR US); **H01C 7/10** (2013.01 - US); **H01C 7/1006** (2013.01 - KR); **H01C 7/102** (2013.01 - EP KR US); **H01C 17/02** (2013.01 - EP KR US); **C08K 3/22** (2013.01 - US); **C08K 2003/2224** (2013.01 - US); **C08K 2003/2227** (2013.01 - US); **H01C 7/1006** (2013.01 - EP US)

Citation (search report)
• [X] WO 2010003278 A1 20100114 - TIANJIN CITY KAIHUA INSULATION [CN], et al
• [X] US 2011274831 A1 20111110 - SAEGUSA KAZUHIRO [JP], et al
• [A] JP 2006328414 A 20061207 - FUKUI PREFECTURE
• [A] EP 0333514 A1 19890920 - MORTILE IND LTD [CA]
• [A] JP 2004281934 A 20041007 - NIPPON CHEMICON
• [A] JP 2005243746 A 20050908 - NIPPON CHEMICON
• [A] JP 2004247479 A 20040902 - NIPPON CHEMICON
• [A] WO 2013074637 A1 20130523 - DOW CORNING [US]
• See references of WO 2015072138A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 3070720 A1 20160921; EP 3070720 A4 20171129; EP 3070720 B1 20190612; CN 105706189 A 20160622; CN 105706189 B 20190503; JP 6561839 B2 20190821; JP WO2015072138 A1 20170316; KR 102181912 B1 20201123; KR 20160083004 A 20160711; TW 201530572 A 20150801; TW I646560 B 20190101; US 2016254081 A1 20160901; US 9892830 B2 20180213; WO 2015072138 A1 20150521

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EP 14862954 A 20141112; CN 201480060992 A 20141112; JP 2014005679 W 20141112; JP 2015547640 A 20141112; KR 20167012114 A 20141112; TW 103139248 A 20141112; US 201615150903 A 20160510